

# SOT467C

CDFM2; blister pack; standard product orientation 12NC  
ending 112

Rev. 1 — 28 November 2012

Packing information

## 1. Packing method

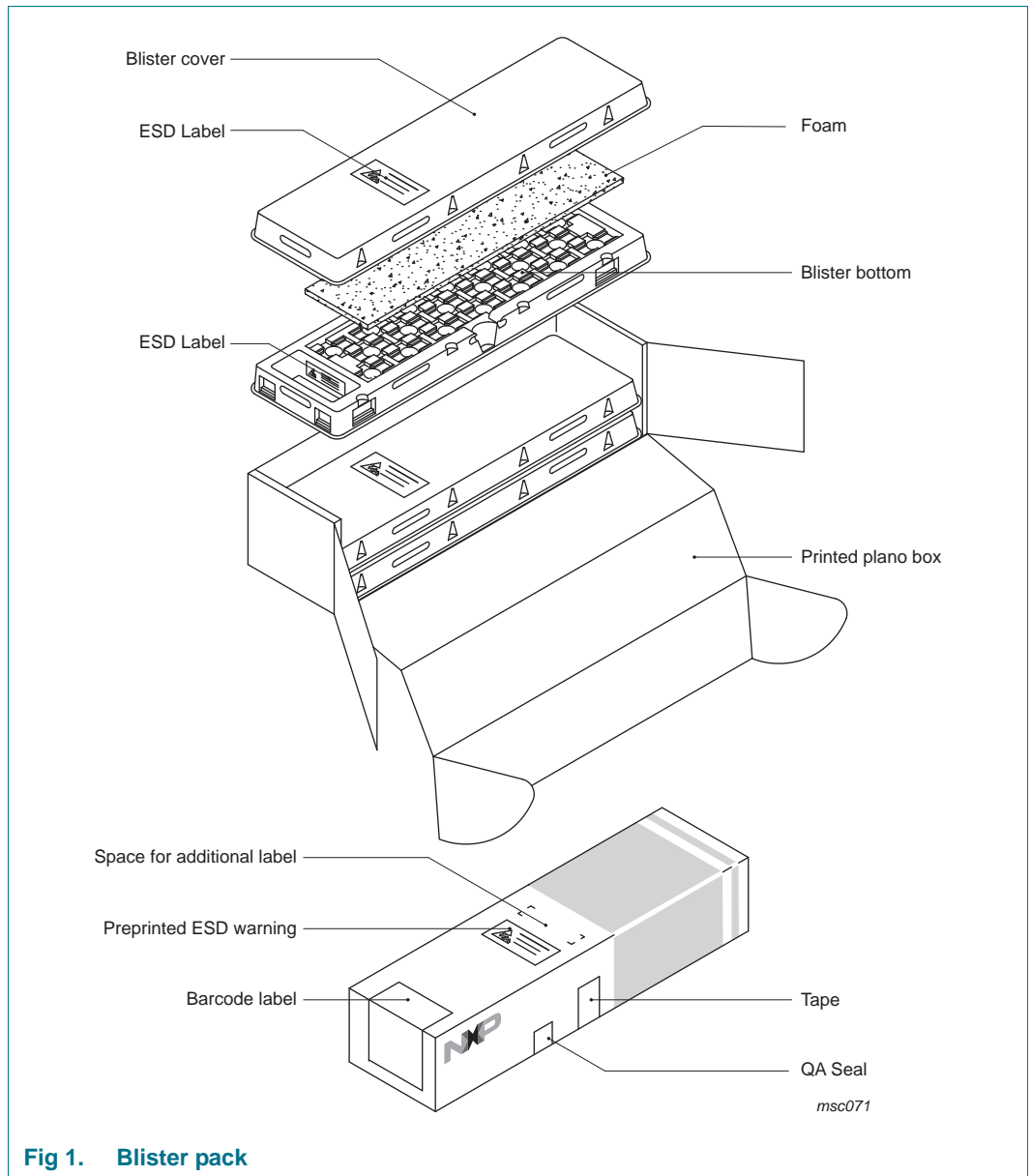


Fig 1. Blister pack

**Table 1. Packing information**

Package version	12NC ending	SPQ per carrier	Carriers per box	PQ (pcs)	Outer box dimensions l x w x h (mm)
SOT467C	112	20	3	60	315 x 118 x 78

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